

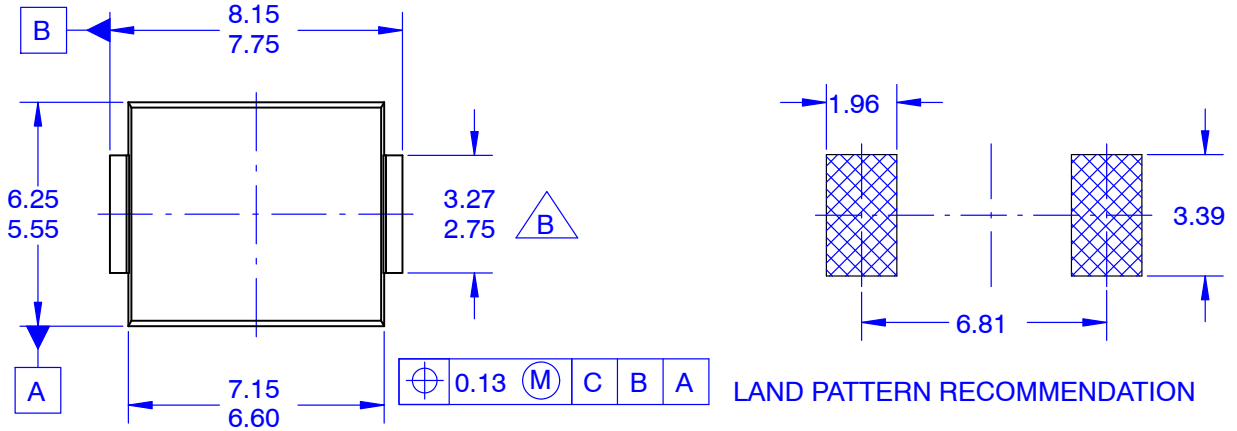
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

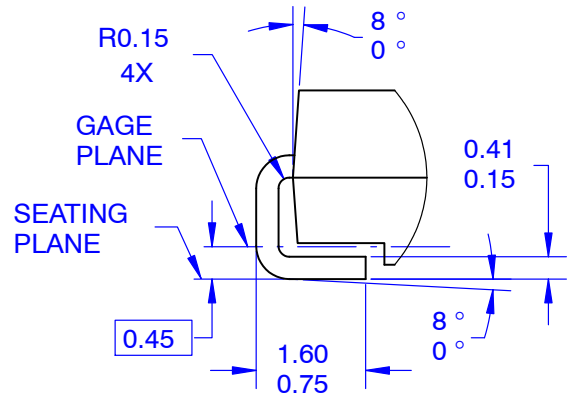
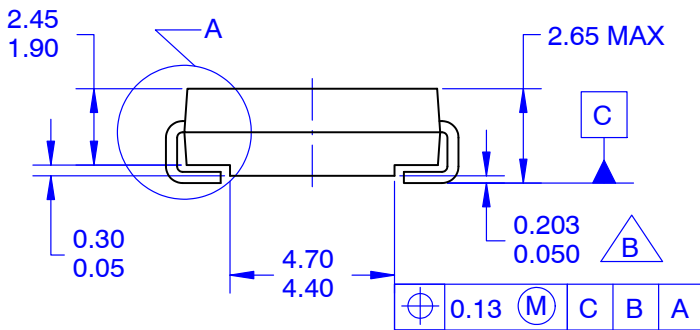


SMC
CASE 403AG
ISSUE O

DATE 31 AUG 2016



TOP VIEW



NOTES:

A. EXCEPT WHERE NOTED, CONFORMS TO JEDEC DO-214, VARIATION AB

- B** DOES NOT COMPLY TO JEDEC STD. VALUE
- C. ALL DIMENSIONS ARE IN MILLIMETERS
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR PROTRUSIONS.
- E. DIMENSIONS AND TOLERANCING AS PER ASME Y14.5-2009
- F. LAND PATTERN STANDARD: DIOM7957X241M

DOCUMENT NUMBER:	98AON13442G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SMC	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.